

# MECHANICAL CASE OUTLINE

## PACKAGE DIMENSIONS

ON Semiconductor®

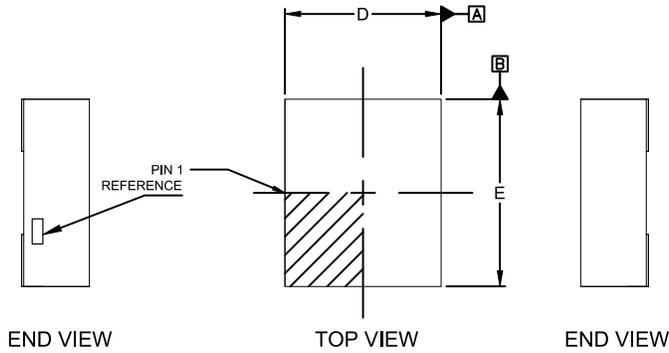


### CWDFN4 1.5x1.8, 0.8P

#### CASE 512AL

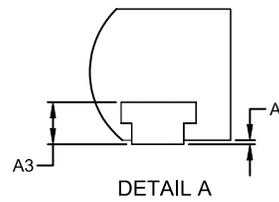
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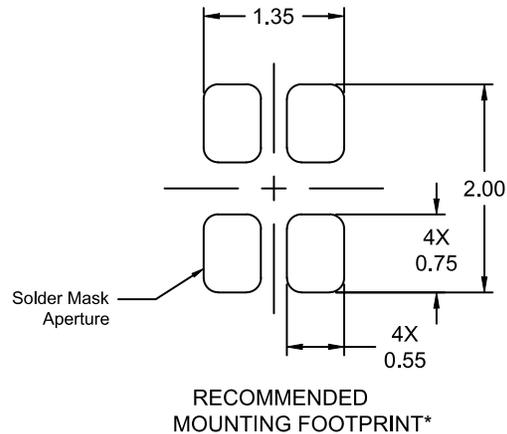
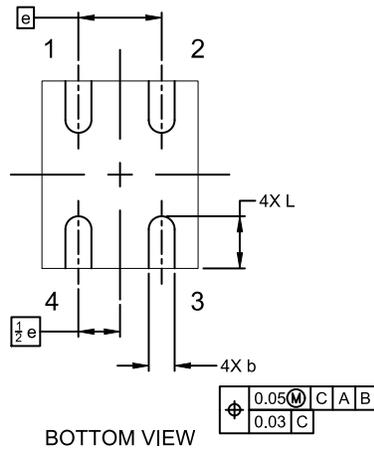
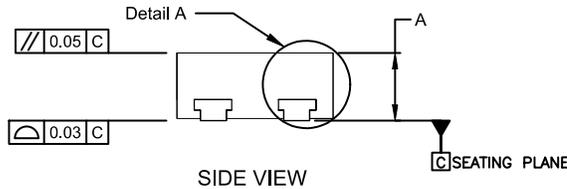


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS



DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.60	0.65	0.70
A1	0.00	---	0.05
A3	0.20 REF		
b	0.20	0.25	0.30
D	1.40	1.50	1.60
E	1.70	1.80	1.90
e	0.80 BSC		
L	0.465	0.515	0.565



\* For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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<b>DESCRIPTION:</b>	<b>CWDFN4 1.5x1.8, 0.8P</b>	<b>PAGE 1 OF 1</b>

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